

Chapter

2

Disassembly (Assembly) Procedure

Please follow the instructions in this section to perform the complete disassembly procedure of the ASUS RTX3070-8G-EK. Before disassembling, be sure to prepare the proper tools.

ASUS Zenbo Junior consists of various modules. This chapter describes the procedures of the each unit component disassembly. Besides, in the process, the detailed disassembly procedure of individual modules will be provided for your service needs.

The disassembly procedure including the following steps:

1. [Service Overview](#)
2. [Remove BACKBOARD](#)
3. [Remove BRAKET](#)
4. [Remove THERMAL Module](#)

Assembly Procedure:

Please read the document in detail, and notice the assembly notice in red frame.

Service Overview

Please pay attention to the cautions below to prevent any damages to the Zenbo-K and also be sure to select the proper tools in this section to perform any services desired.

PRECAUTIONS

Precautions

Before you perform any service and or repair on the Zenbo-K, please follow the steps below:

1. Disconnect the AC plug.
2. Remove all rings, watches and any other metal objects from your hands.



3. Always wear an antistatic wrist strap on your hand to prevent the static discharge.



4. Please refer to “ANSI ESD S20.20” about ESD protection measure.
5. Put the parts you disassembled into the PE BAG for avoid any damages.



6. Environment temperature is 20-30 °C and humidity is 40% - 70%.

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APPROPRIATE
TOOLS

Proper Tools

The following illustrations show what's the proper tools for Zenbo-K repair.

1. Screwdriver

Please according to different screw specifications to choose different screwdriver bits, and these photos are for reference only.

•Cross Screwdriver

Use a cross screwdriver to fasten/remove screws.



(PH0)

Torque range : 0.8kgf +/- 0.1

Check the torque of screwdriver whether it meets the specifications.

•Electric Screwdriver



(PH0)

Torque range 0.8kgf +/- 0.1

2.Glove (PN: 16-TT0E00517)



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DISASSEMBLY**CAUTION**

Disassembly Caution

ASUS hereby provides a basic instruction for the disassembly of ASUS products, i.e. to remove components and materials that require selective treatments, which are defined by Annex II of the European Union (EU) Waste Electrical and Electronic Equipment (WEEE) Directive 2002/96/EC. This instruction is intended for the use of end-of-life recyclers or treatment facilities. Following is the list of Annex II of EU WEEE Directive 2002/96/EC.

- polychlorinated biphenyls (PCB) containing capacitors in accordance with Council Directive 96/59/EC of 16 September 1996 on the disposal of polychlorinated biphenyls and polychlorinated terphenyls (PCB/PCT),
- mercury containing components, such as switches or backlighting lamps,
- batteries,
- printed circuit boards of mobile phones generally, and of other devices if the surface of the printed circuit board is greater than 10 square centimetres,
- toner cartridges, liquid and pasty, as well as colour toner,
- plastic containing brominated flame retardants,
- asbestos waste and components which contain asbestos,
- cathode ray tubes,
- chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC),
- gas discharge lamps,
- liquid crystal displays (together with their casing where appropriate) of a surface greater than 100 square centimeters and all those back-lighted with gas discharge lamps,
- external electric cables,
- components containing refractory ceramic fibres as described in Commission Directive 97/69/EC of 5 December 1997 adapting to technical progress Council Directive 67/548/EEC relating to the classification, packaging and labelling of dangerous substances,
- components containing radioactive substances with the exception of components that are below the exemption thresholds set in Article 3 of and Annex I to Council Directive 96/29/Euratom of 13 May 1996 laying down basic safety standards for the protection of the health of workers and the general public against the dangers arising from ionising radiation,
- electrolyte capacitors containing substances of concern (height > 25 mm, diameter > 25 mm or proportionately similar volume)

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**REMOVE
BACKBOARD**

2. Remove BACKBOARD

The following illustrations show how to remove the BACKBOARD.

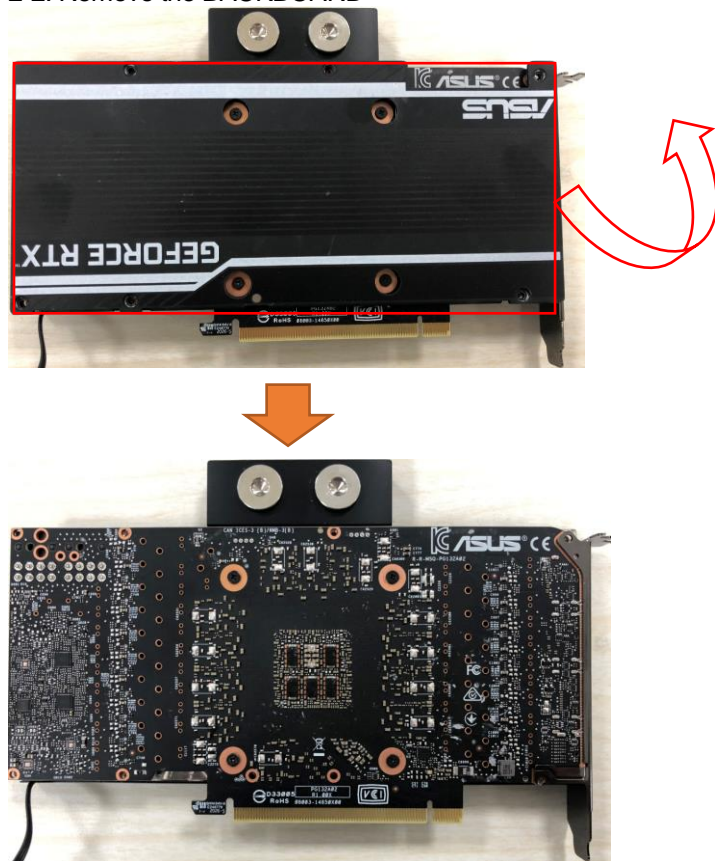
2-1. Remove the six screws on BACKBOARD

2-2. Remove the BACKBOARD

2-1 Use a screwdriver to remove the screws.



2-2. Remove the BACKBOARD



**REMOVE
BRAKET**

3. Remove BRAKET

The following illustrations show how to remove the BRAKET.

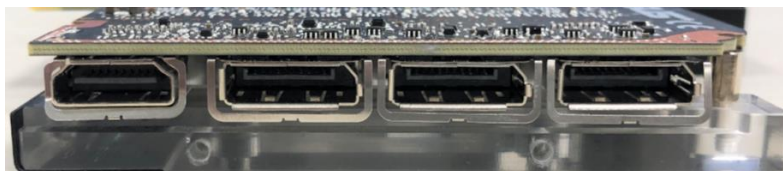
3-1. Remove the two screws on BRAKET.

3-2. Remove the BRAKET.

3-1 Use a screwdriver to remove the screws.



3-2. Remove the BRAKET.



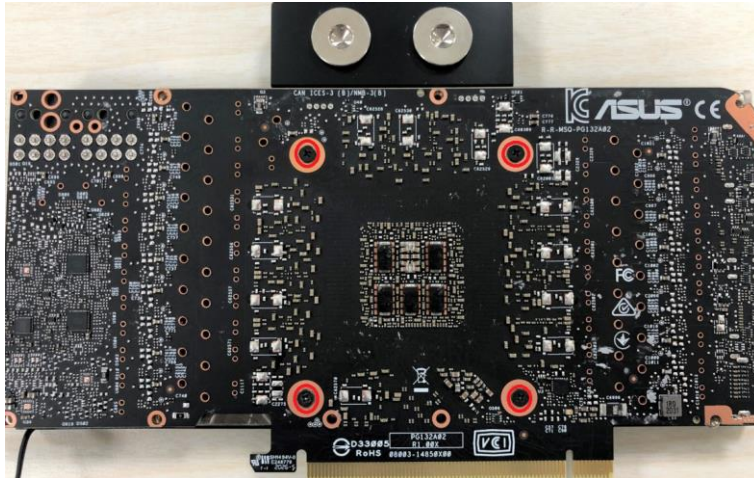
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**REMOVE
THERMAL
MODULE**

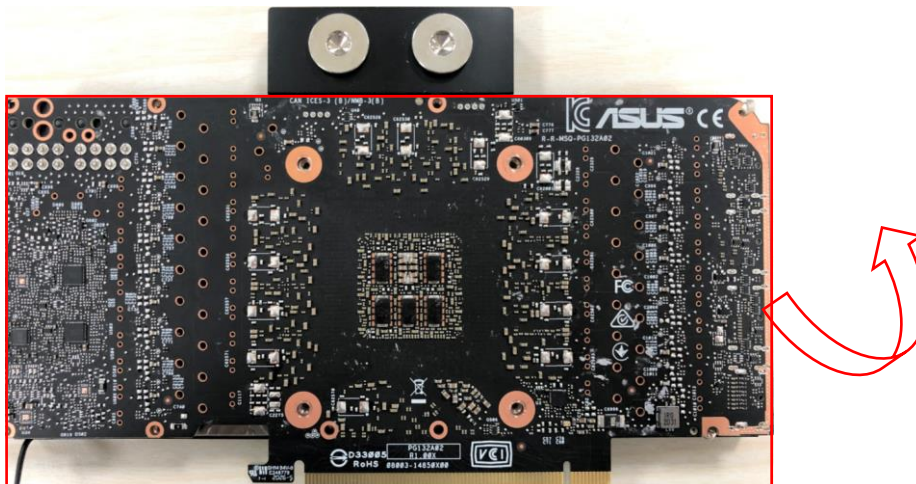
4. Remove THERMAL Module

- 4-1. Remove the four screws on THERMAL Module.
- 4-2. Remove the THERMAL Module.
- 4-3. PCB and THERMAL Module.

4-1 Use a screwdriver to remove the screws.



4-2. Separate PCB and THERMAL Module



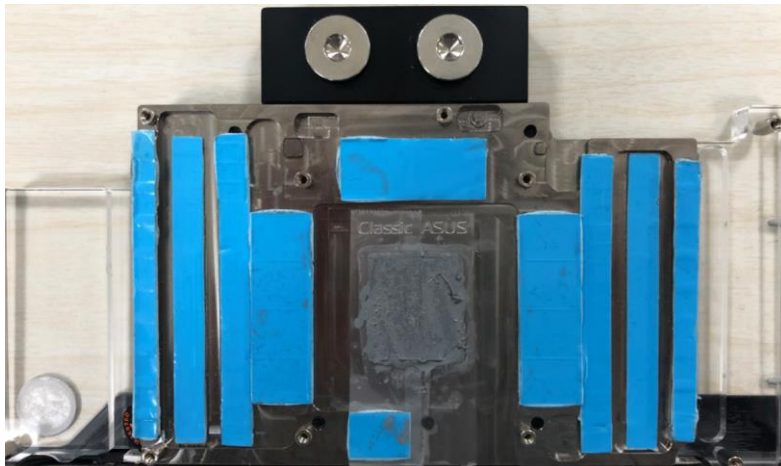
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4-3. PCB and THERMAL Module.

PCB



THERMAL Module.



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